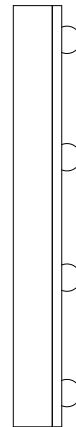
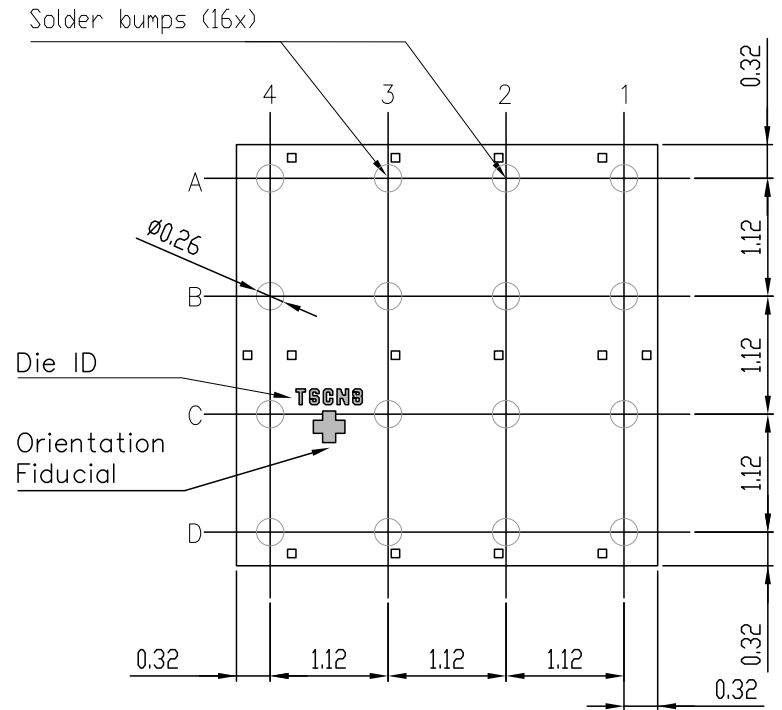


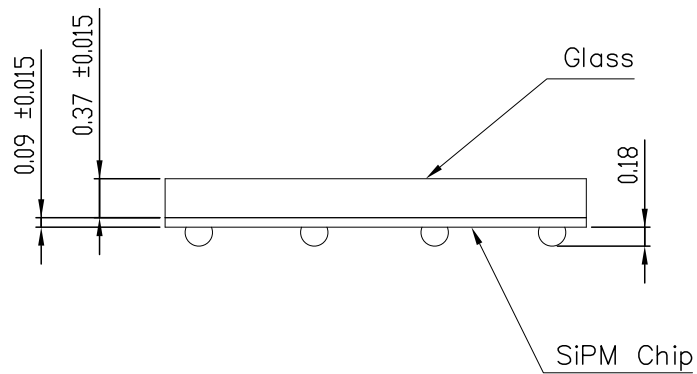
Top View  
Scale 20:1



Side View  
Scale 20:1



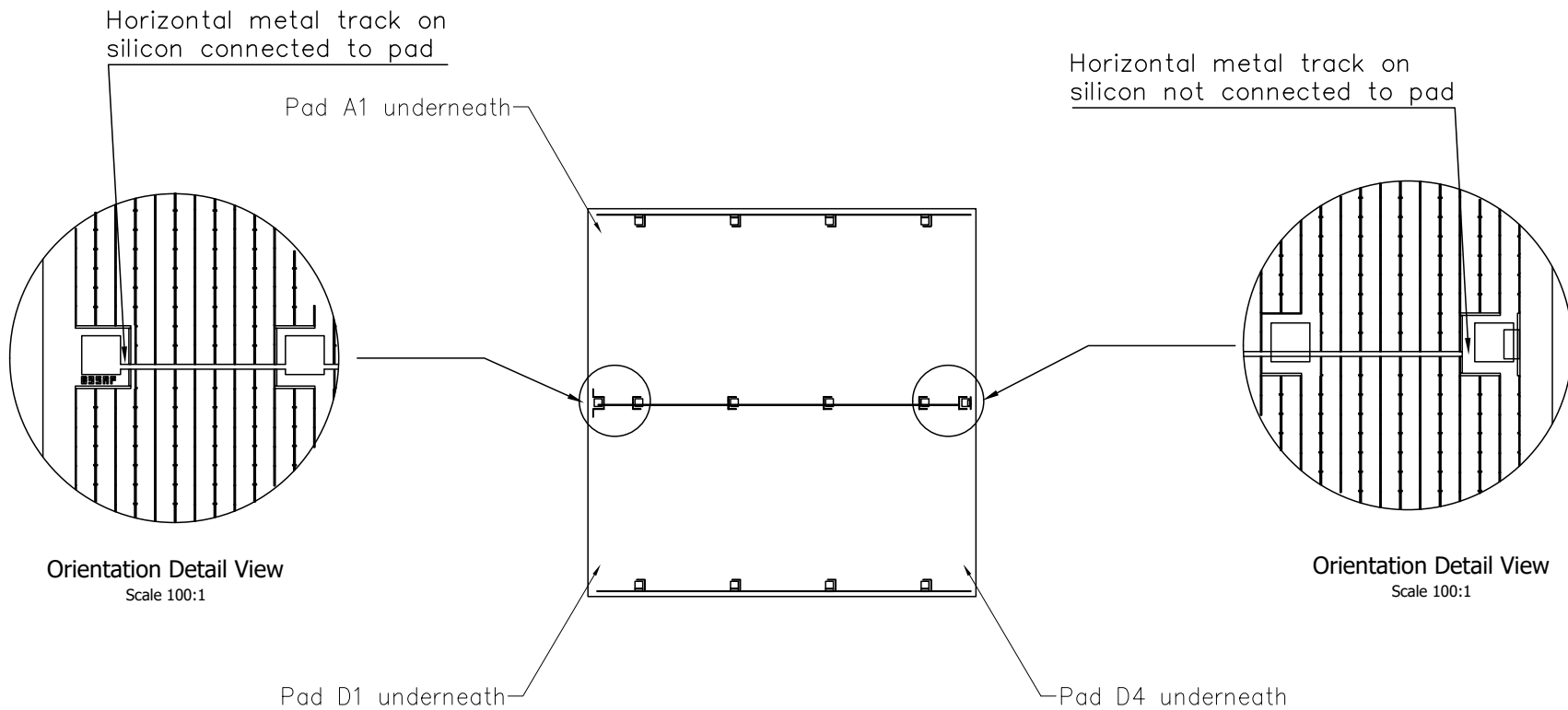
Bottom View  
Scale 20:1



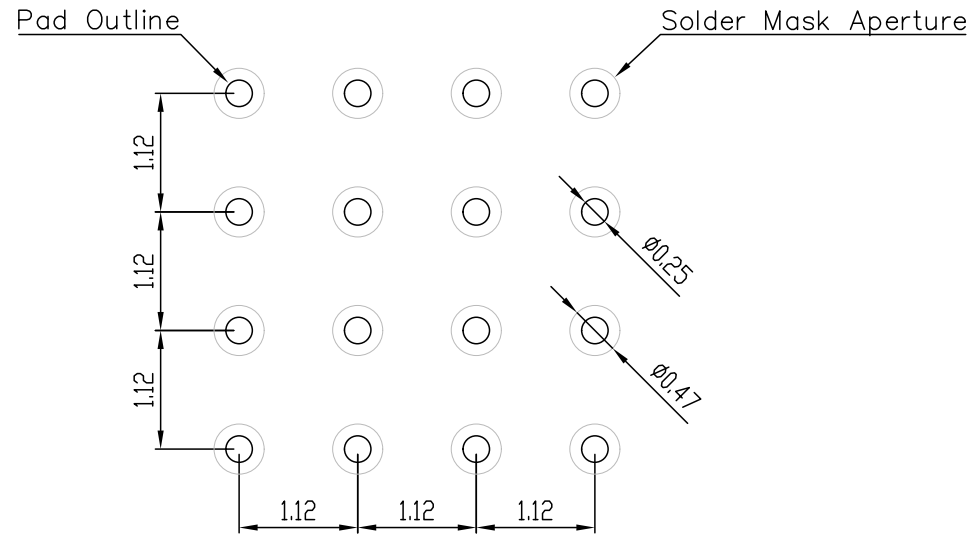
Side View  
Scale 20:1

Pad Assignment			
Pad #	Function	Pad #	Function
A1	Cathode	C1	Anode
A2	No Connect	C2	No Connect
A3	No Connect	C3	No Connect
A4	No Connect	C4	Fast
B1	Anode	D1	No Connect
B2	No Connect	D2	No Connect
B3	No Connect	D3	No Connect
B4	Fast	D4	Cathode

DATE	27 June 2017	REVISION	B	SCALE:	Shown
SensL Technologies Ltd				Sheet 1 of 5	
www.sensl.com					
DWG. NO:	SND0205	DO NOT SCALE	ALL DIMENSIONS IN MM		
TITLE:					
MicroFJ-40035-TSV-A2					
PROJECTION:					



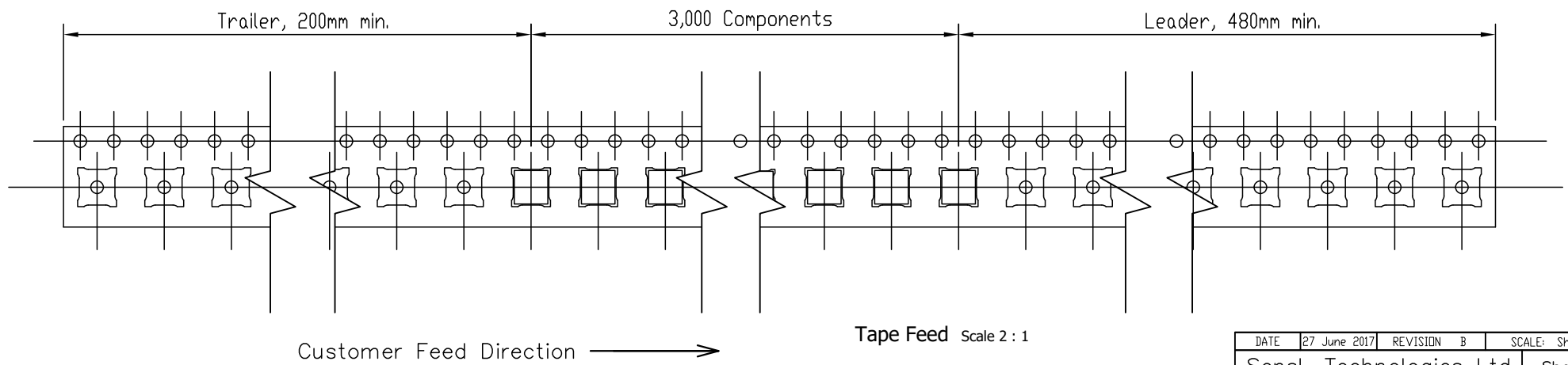
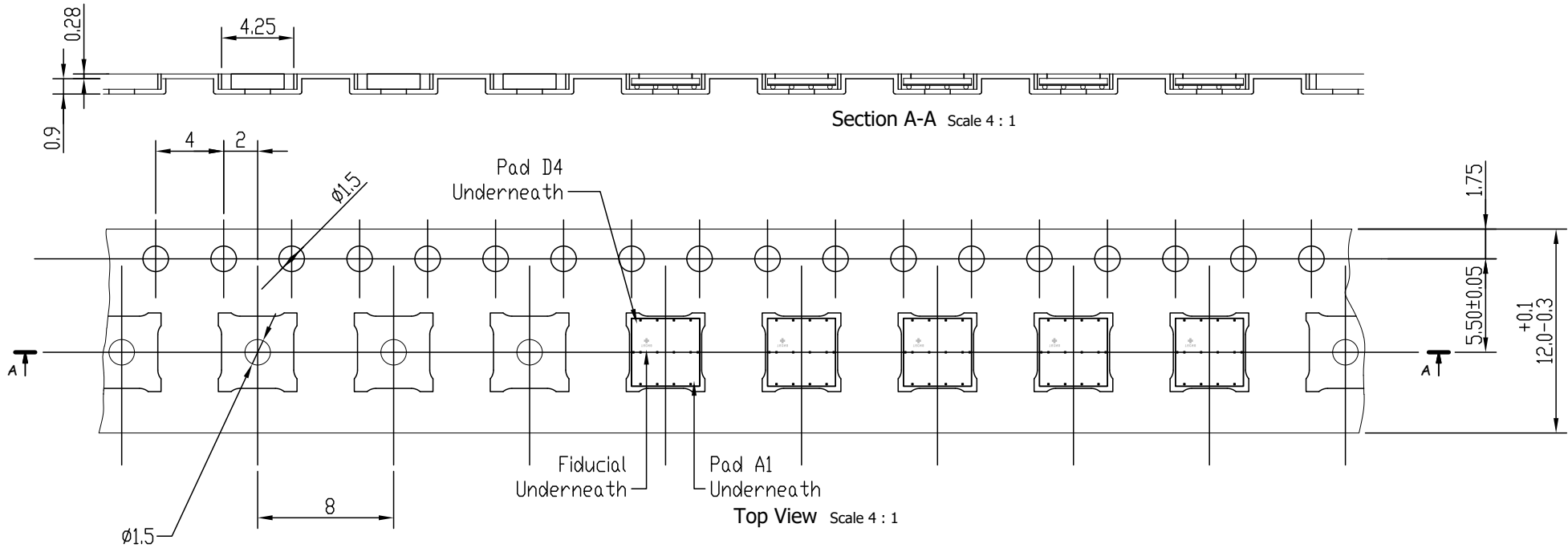
DATE	27 June 2017	REVISION	B	SCALE:	Shown
SensL Technologies Ltd				Sheet	
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DWG. NO:	SND0205	DO NOT SCALE   ALL DIMENSIONS IN MM			
TITLE:					
MicroFJ-40035-TSV-A2					
PROJECTION:					



Recommended PCB Solder Footprint  
Scale 20:1

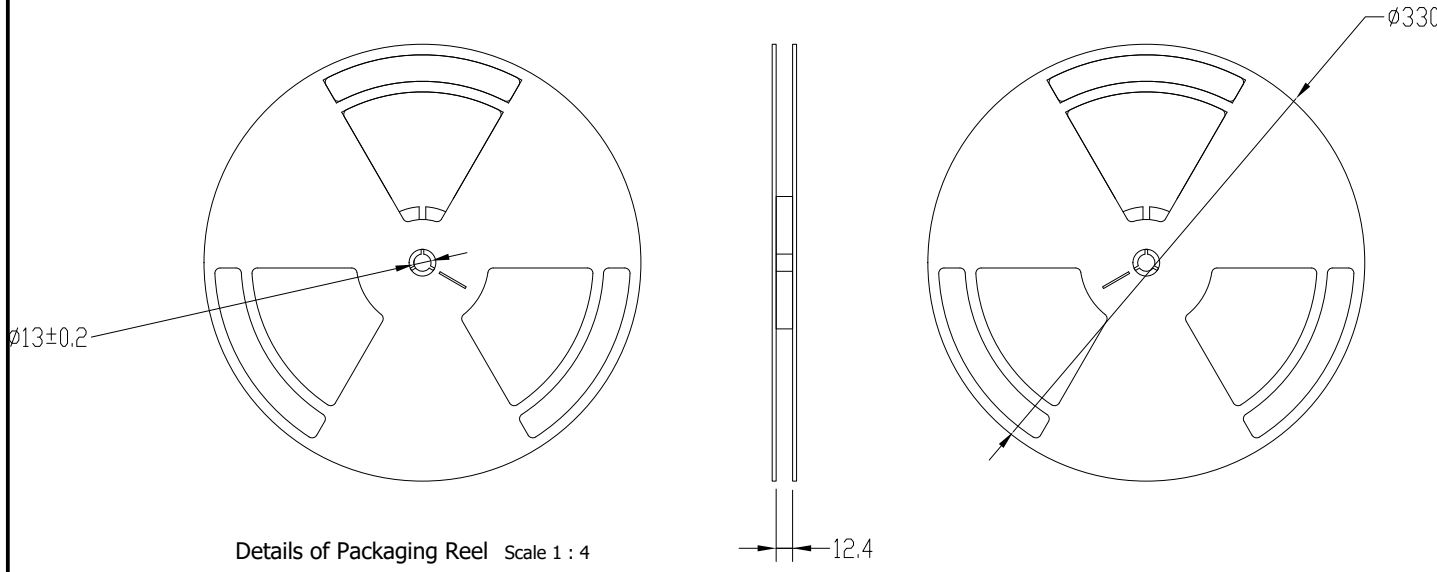
NOTE: The No Connect (NC) pins are electrically isolated and should be soldered to a ground (or bias) plane to help with heat dissipation.

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MicroFJ-40035-TSV-A2					
PROJECTION:					



All Dimensions ± 0.1mm Unless Otherwise Stated

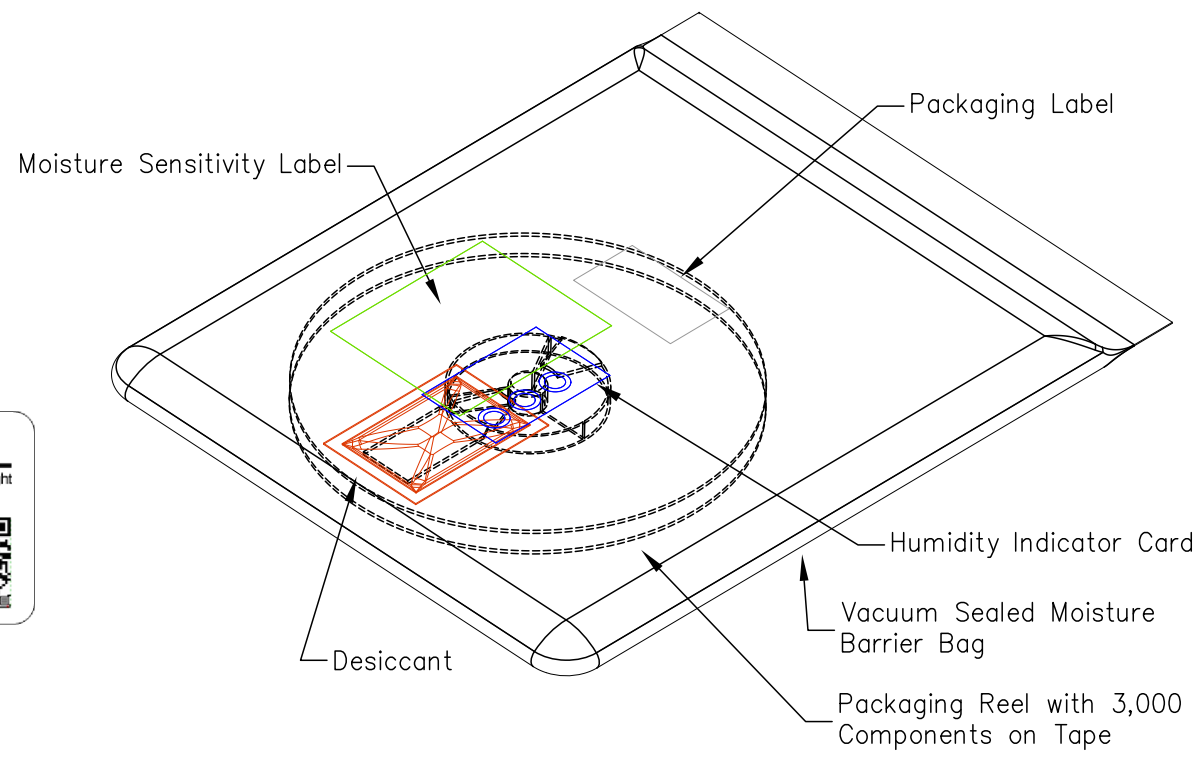
DATE	27 June 2017	REVISION	B	SCALE:	Shown
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www.sensl.com					4 of 5
DWG. NO:	SND0205	DO NOT SCALE ALL DIMENSIONS IN MM			
TITLE:					
MicroFJ-40035-TSV-A2					
PROJECTION:					



Details of Packaging Reel Scale 1 : 4

	<b>CAUTION</b>	<b>3</b>
<b>MOISTURE SENSITIVE DEVICES</b>		
1. Calculated shelf life in sealed bag: 24 months at <math>< 40^{\circ}\text{C}</math> and <math>< 90\%</math> relative humidity (RH)		
2. Peak package body temperature: <u>260</u> $^{\circ}\text{C}$ <small>If blank, see adjacent bar code label</small>		
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be		
a) Mounted within: <u>168</u> hours of factory conditions <math>< 30^{\circ}\text{C}/90\%</math> RH, or		
b) Stored per J-STD-033		
4. Devices require bake, before mounting, if:		
a) Humidity Indicator Card reads > 10% for level 2a - 5a devices or > 60% for level 2 devices when read at <math>25 \pm 5^{\circ}\text{C}</math>		
b) 3a or 3b are not met		
5. If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure		
Bag Seal Date: <u>20 Mar. 2014</u> <small>If blank, see adjacent bar code label</small>		
<small>Note: Level and body temperature defined by IPC/JEDEC J-STD-020</small>		

Details of Moisture Sensitivity Label



5%	10%	60%
<b>LEVEL 2A-5A PARTS</b>		<b>LEVEL 2 PARTS</b>
Bake if 10% IS NOT BROWN and 5% IS AZURE		Bake parts if 60%
DOU YEE ENTERPRISES		IS NOT BROWN
BROWN-DRY	AZURE-WET	
COBALT FREE HUMIDITY INDICATOR CARD		<small>Initial Usage: DO NOT put this card into a bag if 5%, 10% or 60% dot are azure</small>
AVOID METAL CONTACT		
COMPLIES WITH IPC/JEDEC J-STD-033		<b>H16 5 4 3 2 1</b>

Humidity Indicator Card

**Part#: MicroFJ-40035-TSV**  
**Revision: A2**  
**Lot#: E1234-35**  
**Lot#**  
**Quantity: 3000**

Sample Packaging Label

DATE	27 June 2017	REVISION	B	SCALE:	Shown
SensL Technologies Ltd www.sensl.com					Sheet 5 of 5
DWG. NO:	SND0205	DO NOT SCALE ALL DIMENSIONS IN MM			
TITLE:					
<b>MicroFJ-40035-TSV-A2</b>					
PROJECTION:					